



BSI Standards Publication

Electronic components — Long-term storage of electronic semiconductor devices

Part 7: Micro-electromechanical devices

National foreword

This British Standard is the UK implementation of EN IEC 62435-7:2021. It is identical to IEC 62435-7:2020.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Date	Text affected
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English Version

Electronic components - Long-term storage of electronic
semiconductor devices - Part 7: Micro-electromechanical
devices
(IEC 62435-7:2020)

Composants électroniques - Stockage de longue durée des
dispositifs électroniques à semiconducteurs - Partie 7:
Dispositifs microélectromécaniques
(IEC 62435-7:2020)

Elektronische Bauteile - Langzeitlagerung elektronischer
Halbleiterbauelemente - Teil 7: Bauelemente der
Mikrosystemtechnik
(IEC 62435-7:2020)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

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In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC/TR 62258-3 NOTE Harmonized as CLC/TR 62258-3

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60721-3-1	-	Classification of environmental conditions - Part 3-1: Classification of groups of environmental parameters and their severities - Storage	EN IEC 60721-3-1	-
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN IEC 60749-20	-
IEC 60749-20-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat	-	-
IEC 62435-2	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms	EN 62435-2	-
IEC 62435-3	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 3: Data	EN IEC 62435-3	-
IEC 62435-4	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 4: Storage	EN IEC 62435-4	-
IEC 62435-5	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices	EN 62435-5	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE
OF ELECTRONIC SEMICONDUCTOR DEVICES –****Part 7: Micro-electromechanical devices**

FOREWORD

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IEC 62435-7 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

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Draft	Report on voting
47/2664/FDIS	47/2669/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.